

<u>AP6N12MI</u>

120V N-Channel Enhancement Mode MOSFET

Description

The AP6N12MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 120V I_D =6A

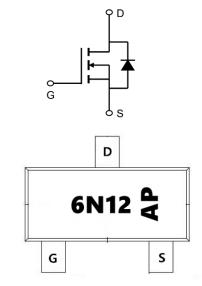
 $R_{DS(ON)} < 180 m \Omega_{OS} = 10V$ (Type: 110mΩ)

Application

Automative lighting

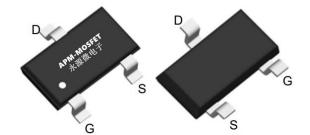
Load switch

Uninterruptible power supply



Top View

Bottom View



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP6N12MI	SOT23-3L	6N12-AP	3000

Absolute Maximum Ratings (TC=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	120	V
VGS	Gate-Source Voltage	±20	V
I⊳@Tc=25°C	Drain Current, V _{GS} @ 10V	6	A
I _D @T _C =100°C	Drain Current, V _{GS} @ 10V	3.5	A
IDM	Pulsed Drain Current ¹	18	A
P₀@Tc=25℃	Total Power Dissipation	30	W
P _D @T _A =25°C	Total Power Dissipation ³	2.7	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
RθJA	Maximum Thermal Resistance, Junctionambient 125		°C/W
RθJC	Maximum Thermal Resistance, Junction-case 5.1		°C/W

<u>AP6N12MI</u>



120V N-Channel Enhancement Mode MOSFET

Electrical Characteristics@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250µA	120	135	-	V
IDSS	Zero Gate Voltage Drain Current	Zero Gate Voltage Drain Current VDS=100V, VGS=0V,		-	1.0	μA
IGSS	Gate to Body Leakage Current	VDS=0V, VGS=±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250µA	1.2	2.0	2.5	V
RDS(on)		VGS=10V, ID=5A	-	110	180	mΩ
	Static Drain-Source on-Resistance note3	VGS=4.5V, ID=3A	-	120	200	mΩ
g fs	Forward Transconductance	V DS =5V , I D =5A		14		S
RG	Gate Resistance	VDS = 0V, VGS =0V,f =1MHz		3		Ω
Ciss	Input Capacitance		-	1100	-	pF
Coss	Output Capacitance	VDS=15V, VGS=0V, f=1.0MHz	-	55	-	pF
Crss	Reverse Transfer Capacitance		-	40	-	pF
Qg	Total Gate Charge	VDS=50V,	-	11.9	-	nC
Qgs	Gate-Source Charge	ID=5A,	-	2.8	-	nC
Qgd	Gate-Drain("Miller") Charge	VGS=10V	-	1.7	-	nC
td(on)	Turn-on Delay Time		-	3.8	-	ns
tr	Turn-on Rise Time	VDS=30V, ID=5A,	-	25.8	-	ns
td(off)	Turn-off Delay Time	RG=1.8Ω, VGS=10V	-	16	-	ns
tf	Turn-off Fall Time		-	8.8	-	ns
IS	Continuous Source Current1,5	VG=VD=0V , Force Current	-	-	14.6	А
ISM	Pulsed Source Current2,5		-	-	25	А
VSD	Diode Forward Voltage2	VGS=0V, IS=10A	-	-	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.

2、The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$

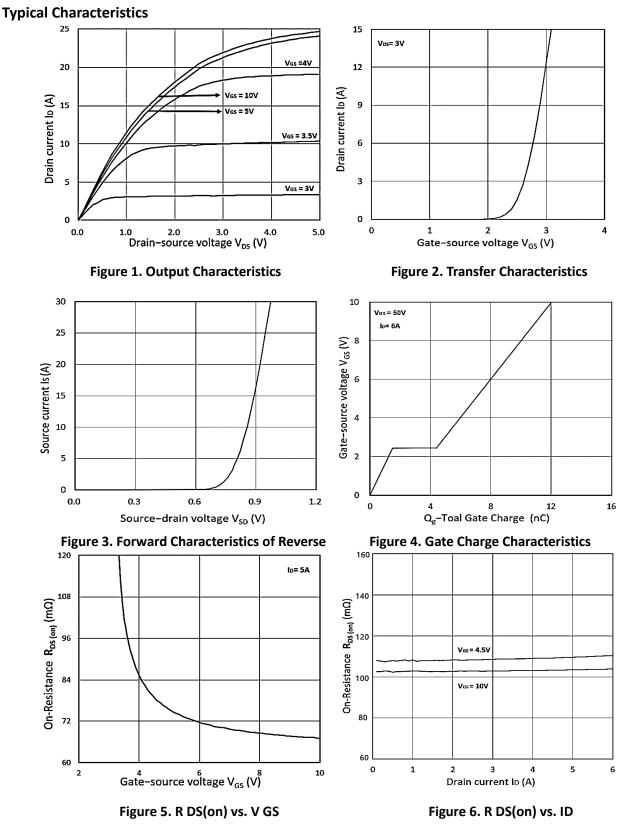
3. The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature

4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.



AP6N12MI

120V N-Channel Enhancement Mode MOSFET





AP6N12MI

120V N-Channel Enhancement Mode MOSFET

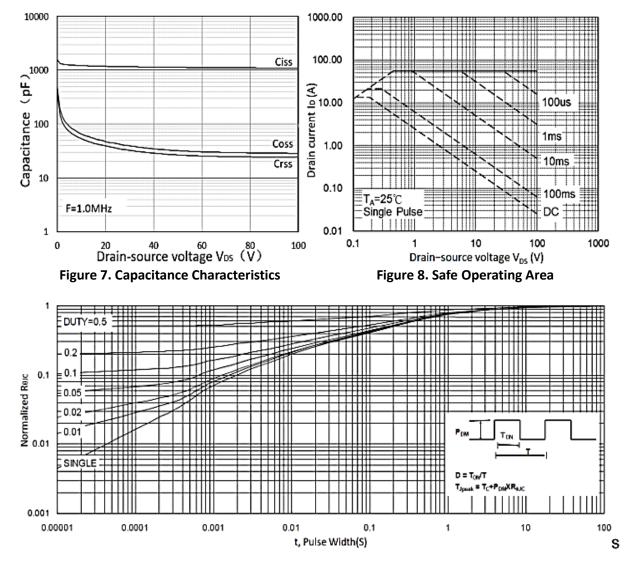
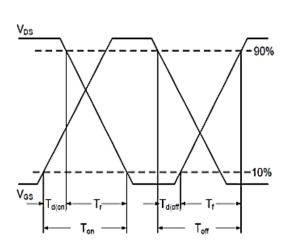
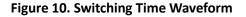


Figure 9. Normalized Maximum Transient Thermal Impedance





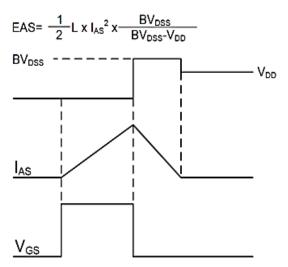
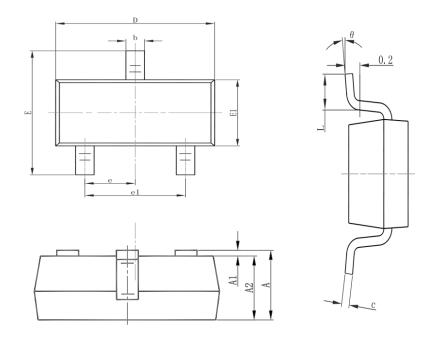


Figure 11. Unclamped Inductive Switching Waveform 🛛 🕂 🔶



120V N-Channel Enhancement Mode MOSFET

Package Mechanical Data-SOT23-3-SLS-Single



C. maked	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
А	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
с	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
е	0.950	(BSC)	0.03	7(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°



120V N-Channel Enhancement Mode MOSFET

Attention

1,Any and all APM Microelectronics products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your APM Microelectronics representative nearest you before using any APM Microelectronics products described or contained herein in such applications.

2,APM Microelectronics assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all APM Microelectronics products described or contained herein.

3, Specifications of any and all APM Microelectronics products described or contained here instipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

4, APM Microelectronics Semiconductor CO., LTD. strives to supply high quality high reliabilityproducts. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. Whendesigning equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

5, In the event that any or all APM Microelectronics products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of APM Microelectronics Semiconductor CO., LTD.

7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. APM Microelectronics believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the APM Microelectronics product that you Intend to use.

D



AP6N12MI

120V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2022/3/15	Initial release

Copyright Attribution"APM-Microelectronice"